MOSFETs Silicon N-Channel MOS (U-MOSVII-H/Schottky Barrier Diode)

# TPCA8A11-H

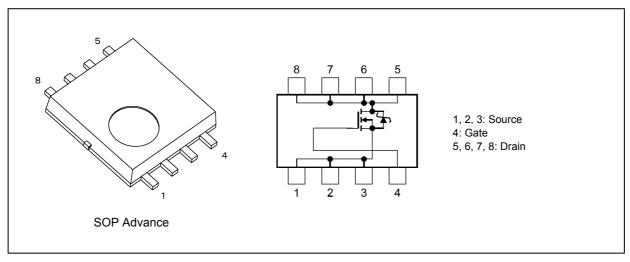
#### 1. Applications

- High-Efficiency DC-DC Converters
- Notebook PCs
- Mobile Handsets

#### 2. Features

- (1) Built-in a schottky barrier diode
  - Low forward voltage:  $V_{DSF}$  = -0.6 V (max)
- (2) High-speed switching
- (3) Small gate charge:  $Q_{SW} = 10 \text{ nC}$  (typ.)
- (4) Low drain-source on-resistance:  $R_{DS(ON)} = 3.5 \text{ m}\Omega$  (typ.) ( $V_{GS} = 4.5 \text{ V}$ )
- (5) Low leakage current:  $I_{DSS} = 100 \ \mu A \ (max) \ (V_{DS} = 30 \ V)$
- (6) Enhancement mode:  $V_{th}$  = 1.3 to 2.3 V ( $V_{DS}$  = 10 V,  $I_D$  = 0.5 mA)

#### 3. Packaging and Internal Circuit



#### 4. Absolute Maximum Ratings (Note) ( $T_a = 25^{\circ}C$ unless otherwise specified)

Characte	Symbol	Rating	Unit		
Drain-source voltage			V <sub>DSS</sub>	30	V
Gate-source voltage			V <sub>GSS</sub>	±20	1
Drain current (DC)		(Note 1)	Ι <sub>D</sub>	35	Α
Drain current (pulsed)		(Note 1)	I <sub>DP</sub>	105	
Power dissipation	(T <sub>C</sub> = 25°C)		PD	52	W
Power dissipation	(t = 10 s)	(Note 2)	PD	2.8	W
Power dissipation	(t = 10 s)	(Note 3)	PD	1.6	W
Single-pulse avalanche energy		(Note 4)	E <sub>AS</sub>	159	mJ
Avalanche current			I <sub>AR</sub>	35	Α
Channel temperature			T <sub>ch</sub>	150	°C
Storage temperature			T <sub>stg</sub>	-55 to 150	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

#### 5. Thermal Characteristics

Characteristics				Max	Unit
Channel-to-case thermal resistance	(T <sub>C</sub> = 25°C)		R <sub>th(ch-c)</sub>	2.4	°C/W
Channel-to-ambient thermal resistance	(t = 10 s)	(Note 2)	R <sub>th(ch-a)</sub>	44.6	°C/W
Channel-to-ambient thermal resistance	(t = 10 s)	(Note 3)	R <sub>th(ch-a)</sub>	78.1	°C/W

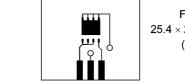
Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: Device mounted on a glass-epoxy board (a), Figure 5.1

Note 3: Device mounted on a glass-epoxy board (b), Figure 5.2

Note 4:  $V_{DD}$  = 24 V,  $T_{ch}$  = 25°C (initial), L = 0.1 mH,  $R_G$  = 1  $\Omega$ ,  $I_{AR}$  = 35 A





 $\begin{array}{c} \text{FR-4} \\ \text{25.4} \times \text{25.4} \times \text{0.8} \\ \text{(Unit: mm)} \end{array}$ 

Fig. 5.1 Device Mounted on a Glass-Epoxy Board (a) Fig. 5.2 Device Mounted on a Glass-Epoxy Board (b)

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.

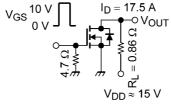
#### 6. Electrical Characteristics

#### 6.1. Static Characteristics (Ta = 25°C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current	I <sub>GSS</sub>	$V_{GS}$ = ±20 V, $V_{DS}$ = 0 V			±0.1	μA
Drain cut-off current	I <sub>DSS</sub>	V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 0 V			100	
Drain-source breakdown voltage	V <sub>(BR)DSS</sub>	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V	30	_	—	V
	V <sub>(BR)DSX</sub>	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = -20 V	15	_	_	
Gate threshold voltage	V <sub>th</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 0.5 mA	1.3	_	2.3	
Drain-source on-resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 17.5 A		3.5	4.6	mΩ
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 17.5 A		2.6	3.6	

### 6.2. Dynamic Characteristics ( $T_a = 25^{\circ}C$ unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Input capacitance	C <sub>iss</sub>	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz		3200	3800	pF
Reverse transfer capacitance	C <sub>rss</sub>	]	_	170	250	
Output capacitance	C <sub>oss</sub>	]		600	_	
Gate resistance	r <sub>g</sub>	$V_{DS}$ = 10 V, $V_{GS}$ = 0 V, f = 5 MHz		1.4	2.1	Ω
Switching time (rise time)	tr	See Figure 6.2.1.	_	4.4	—	ns
Switching time (turn-on time)	t <sub>on</sub>	]		12	_	
Switching time (fall time)	t <sub>f</sub>	]		7.8		
Switching time (turn-off time)	t <sub>off</sub>	]		42	—	



Duty  $\leq$  1%, t<sub>w</sub> = 10  $\mu$ s

#### Fig. 6.2.1 Switching Time Test Circuit

#### 6.3. Gate Charge Characteristics ( $T_a = 25^{\circ}C$ unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Total gate charge (gate-source plus	Qg	$V_{DD}\approx 24~V,~V_{GS} \text{ = } 10~V,~I_{D} \text{ = } 35~A$	_	46	_	nC
gate-drain)		$V_{DD} \approx 24$ V, $V_{GS}$ = 5 V, $I_D$ = 35 A	_	23	—	
Gate-source charge 1	Q <sub>gs1</sub>	$V_{DD} \approx 24$ V, $V_{GS}$ = 10 V, $I_D$ = 35 A		9.7	—	
Gate-drain charge	Q <sub>gd</sub>			5.5	—	
Gate switch charge	Q <sub>SW</sub>			10	—	

#### 6.4. Source-Drain Characteristics ( $T_a = 25^{\circ}C$ unless otherwise specified)

Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Reverse drain current (pulsed) (Net	ote 5)	I <sub>DRP</sub>	—	_	—	105	А
Diode forward voltage		V <sub>DSF</sub>	I <sub>DR</sub> = 1.5 A, V <sub>GS</sub> = 0 V	_	-0.4	-0.6	V
			I <sub>DR</sub> = 35 A, V <sub>GS</sub> = 0 V	_	_	-1.2	

Note 5: Ensure that the channel temperature does not exceed 150°C.

### 7. Marking

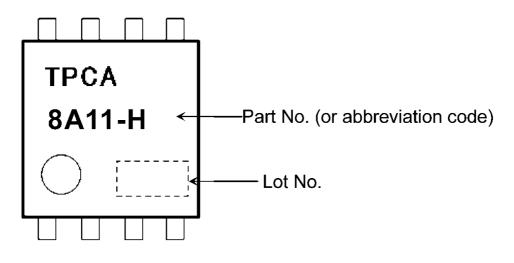
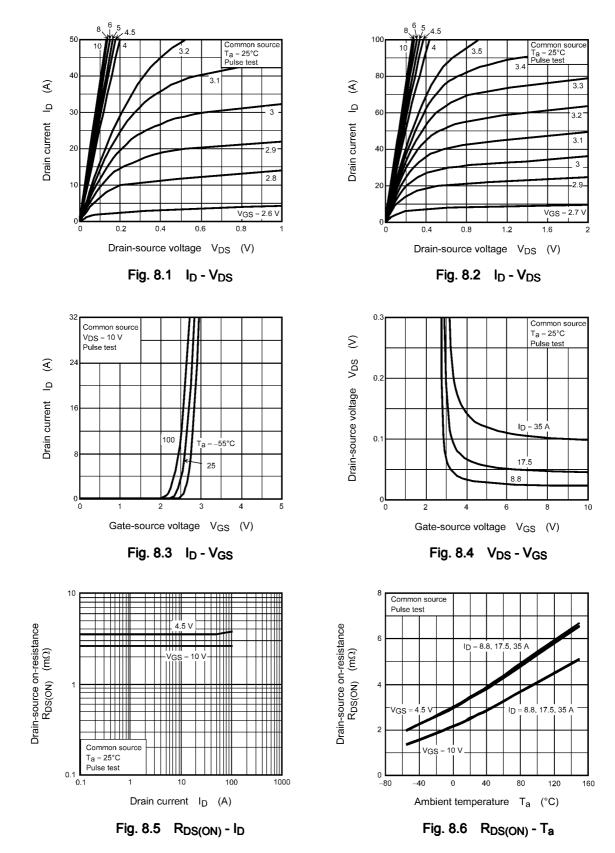
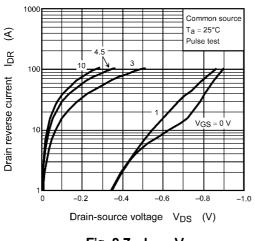


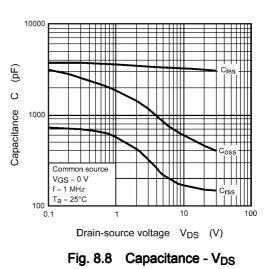
Fig. 7.1 Marking

### 8. Characteristics Curves (Note)









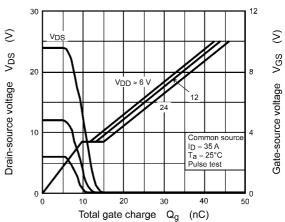
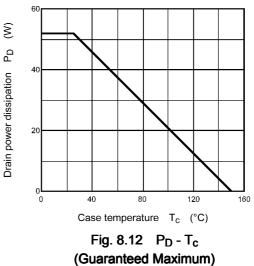
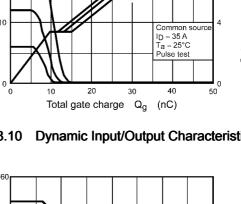
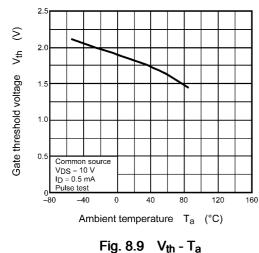


Fig. 8.10 Dynamic Input/Output Characteristics

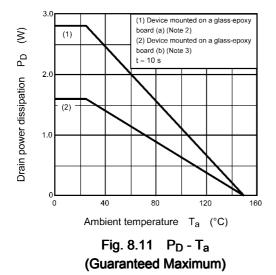


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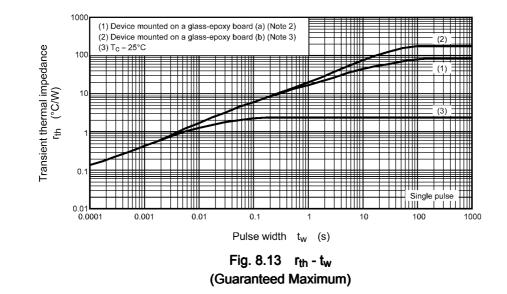


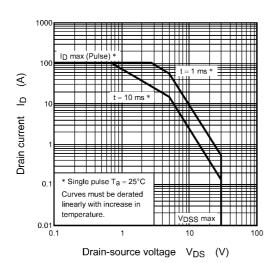


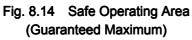












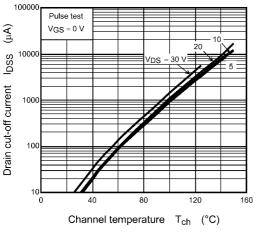
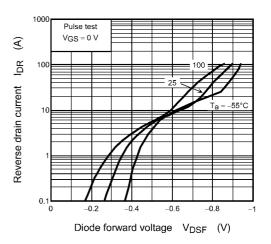
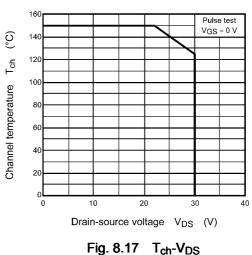


Fig. 8.16 I<sub>DSS</sub>-T<sub>ch</sub>







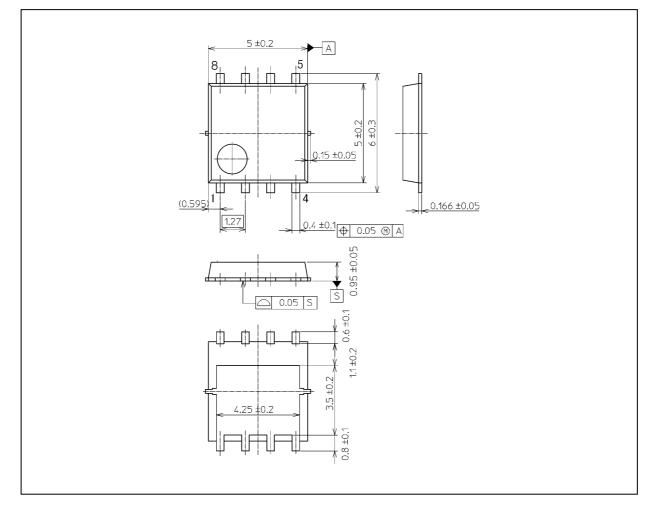
(Guaranteed Maximum)

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

### TPCA8A11-H

#### Package Dimensions

Unit: mm



Weight: 0.069 g (typ.)

Package Name(s)

TOSHIBA: 2-5Q1S

Nickname: SOP Advance

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